

RD Number: RD075

RD Title: TB67S141FTG Evaluation circuit BOM

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	IC1	1	TB67S141FTG	TB67S141FTG	TOSHIBA	Motor driver IC	QFN48	
2	VM	1	Check terminal	—	—	Check terminal for logic		
3	GND	1	Check terminal	—	—	Check terminal for logic		
4	VREF	1	Check terminal	—	—	Check terminal for logic		
5	VDD	1	Check terminal	—	—	Check terminal for oscilloscope		
6	ERR	1	Check terminal	—	—	Check terminal for oscilloscope		
7	ALM	1	Check terminal	—	—	Check terminal for oscilloscope		
8	MO	1	Check terminal	—	—	Check terminal for oscilloscope		
9	LOUT	0	Check terminal	—	—	Check terminal for oscilloscope		✓
10	COUT	0	Check terminal	—	—	Check terminal for oscilloscope		✓
11	DOUT	0	Check terminal	—	—	Check terminal for oscilloscope		✓
12	45	1	Check terminal	—	—	Check terminal for oscilloscope		
13	46	1	Check terminal	—	—	Check terminal for oscilloscope		
14	47	1	Check terminal	—	—	Check terminal for oscilloscope		
15	48	1	Check terminal	—	—	Check terminal for oscilloscope		
16	3	1	Check terminal	—	—	Check terminal for oscilloscope		
17	5	1	Check terminal	—	—	Check terminal for oscilloscope		
18	6	1	Check terminal	—	—	Check terminal for oscilloscope		
19	7	1	Check terminal	—	—	Check terminal for oscilloscope		
20	OUTA+	1	Check terminal	—	—	Check terminal for logic		
21	OUTA-	1	Check terminal	—	—	Check terminal for logic		
22	OUTB+	1	Check terminal	—	—	Check terminal for logic		
23	OUTB-	1	Check terminal	—	—	Check terminal for logic		
24	COMA	1	Check terminal	—	—	Check terminal for logic		
25	COMB	1	Check terminal	—	—	Check terminal for logic		

26	ZD	1	CMZ36	CMZ36	TOSHIBA	Zener diode Vz=36V	M-FLAT	
27	R351	0	Not mount	—	—	Leaded resistor		✓
28	R352	0	Not mount	—	—	Leaded resistor		✓
29	R37	1	10kΩ	—	—	Leaded resistor		
30	R38	1	10kΩ	—	—	Leaded resistor		
31	R39	1	10kΩ	—	—	Leaded resistor		
32	R40	1	10kΩ	—	—	Leaded resistor		
33	C312	1	0.1μF 50V	—	—	Chip capacitor	3.2mm×1.6mm	
34	C33	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
35	C35	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
36	CDD	1	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	
37	C13	0	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	✓
38	C17	0	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	✓
39	C19	0	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	✓
40	C23	0	0.1μF 25V	—	—	Chip capacitor	3.2mm×1.6mm	✓
41	C311	1	100μF 50V	—	—	Electrolytic capacitor		
42	SW3	1	Pin header 3P	—	—	Single row plugs		
43		1	Jump socket	—	—	Position Shunt Connector		
44	SW5	1	Pin header 3P	—	—	Single row plugs		
45		1	Jump socket	—	—	Position Shunt Connector		
46	SW6	1	Pin header 3P	—	—	Single row plugs		
47		1	Jump socket	—	—	Position Shunt Connector		
48	SW7	1	Pin header 3P	—	—	Single row plugs		
49		1	Jump socket	—	—	Position Shunt Connector		
50	SW45	0	Pin header 3P	—	—	Single row plugs		✓
51		0	Jump socket	—	—	Position Shunt Connector		✓
52	SW46	0	Pin header 3P	—	—	Single row plugs		✓
53		0	Jump socket	—	—	Position Shunt Connector		✓
54	SW47	1	Pin header 3P	—	—	Single row plugs		
55		1	Jump socket	—	—	Position Shunt Connector		
56	SW48	1	Pin header 3P	—	—	Single row plugs		
57		1	Jump socket	—	—	Position Shunt Connector		



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